

Application No. 10/664,169

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS:

1) (Currently Amended) A porous material bonded to a substantially non-porous material comprising:

a) a substantially non-porous substrate having a bonding surface and a plurality of substrate apertures, each aperture having an aperture width and an aperture depth, extending partially through said non-porous substrate, and at least partially filled with an adhesive in the bonding surface and,

b) a porous material bonded to the bonding surface with a portion of the adhesive wicked into the porous substrate.

2) (Previously Presented) The porous material bonded to a substantially non-porous material of claim 1 wherein there is a residue of adhesive on the bonding surface.

3) (Previously Presented) The porous material bonded to a substantially non-porous material of claim 1 wherein the aperture width is at least approximately 0.5 microns.

4) (Previously Presented) The porous material bonded to a substantially non-porous material of claim 1 wherein the aperture depth is at least approximately 0.5 microns.

Application No. 10/664,169

5) (Previously Presented) The porous material bonded to a substantially non-porous material of claim 1 further comprising at least one substrate groove having a groove width and a groove depth on the bonding surface.

6) (Previously Presented) The porous material bonded to a substantially non-porous material of claim 5 wherein the at least one substrate groove extends between at least two substrate apertures.

7) (Previously Presented) The porous material bonded to a substantially non-porous material of claim 5 wherein the groove depth is at least approximately 0.5 microns.

8) (Previously Presented) The porous material bonded to a substantially non-porous material of claim 5 wherein the groove width is at least approximately 0.5 microns.

9) (Previously Presented) The porous material bonded to a substantially non-porous material of claim 1 wherein the substrate apertures comprise no more than approximately 50% of the bonding surface.

10) (Canceled)

11) (New) A porous material bonded to a substantially non-porous material comprising:

a) a substantially non-porous substrate having an aperture portion and a remainder portion adjacent to each other, a bonding surface being a surface of the aperture portion, and a plurality of substrate apertures extending from the bonding surface through the aperture portion, each aperture having an aperture width and an aperture depth, extending partially through said non-

Application No. 10/664,169

porous substrate, and at least partially filled with an adhesive in the bonding surface and,

b) a porous material bonded to the bonding surface with a portion of the adhesive wicked into the porous substrate.

12) (New) The porous material bonded to a substantially non-porous material of claim 1 wherein there is a residue of adhesive on the bonding surface.

13) (New) The porous material bonded to a substantially non-porous material of claim 1 wherein the aperture width is at least approximately 0.5 microns.

14) (New) The porous material bonded to a substantially non-porous material of claim 1 wherein the aperture depth is at least approximately 0.5 microns.

15) (New) The porous material bonded to a substantially non-porous material of claim 1 further comprising at least one substrate groove having a groove width and a groove depth on the bonding surface.

16) (New) The porous material bonded to a substantially non-porous material of claim 5 wherein the at least one substrate groove extends between at least two substrate apertures.

17) (New) The porous material bonded to a substantially non-porous material of claim 5 wherein the groove depth is at least approximately 0.5 microns.

18) (New) The porous material bonded to a substantially non-porous material of claim 5 wherein the groove width is at least approximately 0.5 microns.

Application No. 10/664,169

19) (New) The porous material bonded to a substantially non-porous material of claim 1 wherein the substrate apertures comprise no more than approximately 50% of the bonding surface.